

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S199	2027	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/07 11:21
S200	10727	(coat\$4 or laminat\$4) near8 (copper near4 (sheet or foil)) same (substrate or wafer or carrier or handler or support\$4 or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/07 11:22
S201	7	S199 and S200	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/07 11:24
S202	8551	(257/700,701,762,758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/07 11:24
S203	70519	(copper or Cu or foil) near8 laminat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/07 11:25
S204	428	S202 and S203	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/07 11:25
S205	5	("20020000654"   "20030168969"   "5639989"   "6150193"   "6414382").PN. OR ("7087987"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/07 11:29
S206	7	("6303523"   "6333255"   "6348725").PN. OR ("6614096"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/07 12:23
S207	2	("5904556").PN. OR ("6545362"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/07 12:45

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S20 8	6260	(coat\$4 or apply\$4 or applied or deposit\$4 or overlay\$4) near8 (insulation or insulator or insulating or dielectric or carrier or substrate or holder or handler or board or support\$4) near20 (copper or Cu or foil) same laminat\$4	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/07 12:46
S20 9	170	S208 and (recrystal\$6 or re-crystal\$6)	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/07 12:58
S21 0	2044	(257/700).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/07 13:00
S21 1	460	(heat\$4 or anneal\$4 or (hot near4 press\$4) or thermal\$4 or treat\$4) near20 (copper or Cu or foil) near20 (recrystal\$6 or re-crystal\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/07 14:51
S21 2	1480	(257/701).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/07 14:51
S21 3	2	S212 and ((heat\$4 or anneal\$4 or (hot near4 press\$4) or thermal\$4 or treat\$4) near20 (copper or Cu or foil) near20 (recrystal\$6 or re-crystal\$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/07 14:51